

IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A ~~multiplayer~~ multilayer circuit board, comprising:
 - a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;
 - a ~~multiplayer~~ multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit pattern and an insulation layer formed on said conductive layer by film formation;
 - a second conductive layer formed on the second surface of said substrate, by which said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers, wherein the second surface of said substrate includes a side surface of a projection on the first surface,

wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and

wherein the required angle between the first and second surfaces is an obtuse angle.
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Currently Amended) A ~~multiplayer~~ multilayer circuit board, comprising:
 - a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;
 - a ~~multiplayer~~ multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit ~~patter~~ pattern and an insulation layer formed on said conductive layer by film formation;

a second conductive layer formed on the second surface of said substrate, by which a layer-to-layer connection of said multilayer circuit is made, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive layer formed on an inner surface of said concave.

wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and wherein the required angle between the first and second surfaces is an obtuse angle.

6. (Original) The multilayer circuit board as set forth in claim 1, wherein said second conductive layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of said conductive layers is separated from an adjacent second conductive layer in the thickness direction by a second insulation layer.
7. (Currently Amended) A ~~multiplayer~~ multilayer circuit board, comprising:
 - a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;
 - a ~~multiplayer~~ multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit ~~patter~~ pattern and an insulation layer formed on said conductive layer by film formation;
 - a second conductive layer formed on the second surface of said substrate, by which a layer-to-layer connection of said multilayer circuit is made, wherein said substrate has a third surface extending at a different level from the first surface and a fourth surface extending from the other end of the first surface to an end of the third surface, and said multilayer circuit is formed on the first, third, and fourth surfaces of said substrate, and said second conductive layer is formed on the second surface that is a side

surface of a projection on the first surface to make the layer-to-layer connection of said multilayer circuit,

wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and

wherein the required angle between the first and second surfaces is an obtuse angle.

8. (New) A multilayer circuit board comprising:

a substrate having a first surface and a projection formed on the first surface;

a pair of multilayer circuits formed on the first surface at both sides of said projection, each of said multilayer circuits composed of a plurality of circuit layers, each of which is provided with a conductive-metal layer having a required circuit pattern and an insulation layer formed on said conductive-metal layer by film formation; and

a second conductive-metal layer successively formed on side and top surfaces of said projection,

wherein said conductive-metal layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive-metal layer on the side surface of said projection, and one of the pair of multilayer circuits is electrically connected to the other one by said second conductive-metal layer on the side and top surfaces of said projection,

wherein an angle between the side surface of said projection and the first surface is an obtuse angle.

9. (New) The multilayer circuit board as set forth in claim 8, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive-metal layer formed on an inner surface of said concave.

10. (New) The multilayer circuit board as set forth in claim 8, wherein said second conductive-metal layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of second conductive-metal layers is separated from an adjacent second conductive-metal layer in the thickness direction by a second insulation layer.
11. (New) The multilayer circuit board as set forth in claim 8, comprising a third conductive-metal layer for forming another layer-to-layer connection of said multilayer circuit, which is formed on a side surface of said substrate extending adjacent to the first surface.